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Non-halogen resin composition, used for pressure sensitive adhesive tapes for binding electric wires of automobiles, comprises plasticizers in a resin consisting of polyolefin resins and inorganic flame retardants
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Patent Family

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Patent Details

Patent	Kind	Language	Page	Main IPC	Filing Notes
JP 2001131509	A		5	C09J-007/02	

Abstract:

JP 2001131509 A

NOVELTY Novel non-halogen resin composition (P1), used for pressure sensitive adhesive tapes, consists of plasticizer(s) (A) (3-5 parts weight) in a non-halogen resin composition (B) that comprises polyolefin type resin(s) (B1) (100 parts weight) and inorganic flame retardant(s) (B2) (60-150 parts weight).

DETAILED DESCRIPTION An **INDEPENDENT CLAIM** is also included for (i) a film (P2) obtained by molding (P1); and (ii) a pressure sensitive adhesive tape (P3) consisting of a tape obtained by cutting (P2) and an acrylic pressure sensitive adhesive layer formed on one surface of the tape.

USE The non-halogen resin composition (P1) is suitable for manufacture of a film (P2). The film (P2) is suitable for manufacture of a pressure sensitive adhesive tape (P3). The pressure sensitive adhesive tape (P3) is suitable as a flame retardant pressure sensitive adhesive tape for binding electric wires for automobiles.

ADVANTAGE The produced pressure sensitive adhesive tape (P3) has secured tack and pressure sensitive adhesiveness at least equivalent to those properties of conventional halogenated vinyl resin base pressure sensitive adhesive tapes by making plasticizer contained in the tape migrate into the pressure sensitive adhesive layer.

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Technology Focus: